

Electronic Patent Application Fee Transmittal

Application Number:	10663967			
Filing Date:	16-Sep-2003			
Title of Invention:	METHODS OF FABRICATING INTEGRATED CIRCUIT DEVICES HAVING FUSE STRUCTURES INCLUDING BUFFER LAYERS			
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Filer:	Elizabeth A. Stanek/Erin Dutton			
Attorney Docket Number:	5649-1161			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
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Total in USD (\$)				1700